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Docket No. 59744 (71987)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT: C. Huang et al.

U.S. SERIAL NO: 10/643,375

EXAMINER: D. Owens

FILED: August 18, 2003

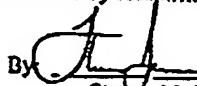
GROUP: 2811

FOR: SEMICONDUCTOR PACKAGE HAVING CONDUCTIVE BUMPS ON
CHIP AND METHOD FOR FABRICATING THE SAME

entered by RCE
filed 7/18/05
S. Davis
8/24/05

CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper (along with any paper referred to as being attached or enclosed) is being transmitted by facsimile to the U.S. Patent & Trademark Office by facsimile number 571-273-8300 on July 18, 2005.

By 
Steven M. Jensen

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

AMENDMENT

Applicants are in receipt of the Office Action dated April 18, 2005 of the above-referenced application. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 7 of this paper.